

TQP7M9106

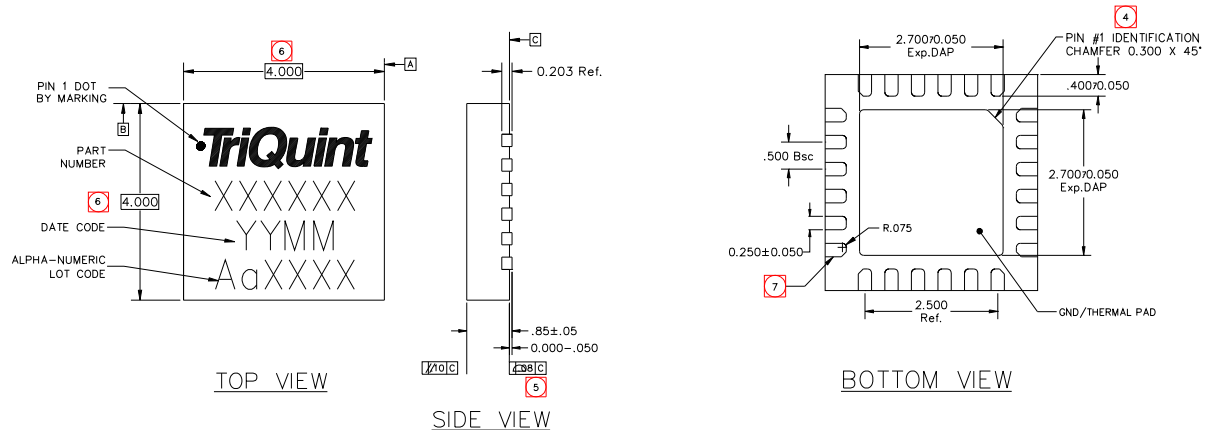
2W High Linearity Amplifier



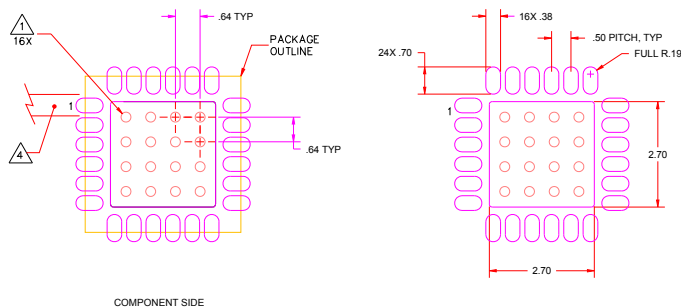
Mechanical Information

Package Information and Dimensions

The component will be marked with a "7M9106" designator and an alphanumeric lot code on the top surface of package.



PCB Mounting Pattern



NOTES:

1. GROUND/THERMAL VIAS ARE CRITICAL FOR THE PROPER PERFORMANCE OF THIS DEVICE. VIAS SHOULD USE A .35mm (#80/.0135") DIAMETER DRILL AND HAVE A FINAL, PLATED THRU DIAMETER OF .25mm (.010").
2. ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
3. TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE-TO-GROUND PAD SOLDER JOINT IS CRITICAL.
4. RF TRACE WIDTH DEPENDS UPON THE PC BOARD MATERIAL AND CONSTRUCTION.
5. USE 1 OZ. COPPER MINIMUM.
6. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

NOTES:

1. All dimensions are in millimeters [inches]. Angles are in degrees.
2. Use 1 oz. copper minimum for top and bottom layer metal.
3. Vias are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25mm (0.10").
4. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.
5. Place mounting screws near the part to fasten a back side heat sink.
6. Do not apply solder mask to the back side of the PC board in the heat sink contact region.
7. Ensure that the backside via region makes good physical contact with the heat sink.